

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Hideki MURATA</td> <td>01/11/2008</td> </tr> <tr> <td>Tsuyoshi MOKUDAI</td> <td>01/12/2008</td> </tr> <tr> <td>Michio SHIOMI</td> <td>01/07/2008</td> </tr> </tbody> </table>		Name	Execution Date	Hideki MURATA	01/11/2008	Tsuyoshi MOKUDAI	01/12/2008	Michio SHIOMI	01/07/2008
Name	Execution Date								
Hideki MURATA	01/11/2008								
Tsuyoshi MOKUDAI	01/12/2008								
Michio SHIOMI	01/07/2008								
RECEIVING PARTY DATA									
Name:	Kyowa Hakko Kogyo Co., Ltd.								
Street Address:	6-1, Ohtemachi 1-chome								
Internal Address:	Chiyoda-ku								
City:	Tokyo								
State/Country:	JAPAN								
Postal Code:	1008185								
PROPERTY NUMBERS Total: 1									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12063318</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12063318				
Property Type	Number								
Application Number:	12063318								
CORRESPONDENCE DATA									
Fax Number:	(312)616-5700								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
Phone:	312-616-5600								
Email:	assignments@leydig.com								
Correspondent Name:	LEYDIG VOIT & MAYER, LTD								
Address Line 1:	TWO PRUDENTIAL PLAZA, SUITE 4900								
Address Line 2:	180 NORTH STETSON AVENUE								
Address Line 4:	CHICAGO, ILLINOIS 60601-6731								
ATTORNEY DOCKET NUMBER:	702553								
NAME OF SUBMITTER:	John Kilyk, Jr.								
Total Attachments: 2									

CH \$40.00 12063318

source=Assignment#page1.tif
source=Assignment#page2.tif

Leydig, Voit & Mayer, Ltd.
Attorneys at Law
Two Prudential Plaza
Suite 4900
180 North Stetson
Chicago, Illinois 60601-6780

ASSIGNMENT OF APPLICATION FOR PATENT

WHEREAS, WE,

Hideki MURATA of c/o Hofu Plant, KYOWA HAKKO KOGYO CO., LTD., 1-1, Kyowa-cho, Hofu-shi, Yamaguchi 747-8522 Japan

(full name and address, including postal code, of first inventor)

Tsuyoshi MOKUDAI of c/o Hofu Plant, KYOWA HAKKO KOGYO CO., LTD., 1-1, Kyowa-cho, Hofu-shi, Yamaguchi 747-8522 Japan

(full name and address, including postal code, of second inventor)

Michio SHIOMI of 9673, Kido, Yokoshibahikari-machi, Yamabu-gun, Chiba 289-1726 Japan

(full name and address, including postal code, of third inventor)

respectively, have invented and own a certain new and useful invention entitled:

METHOD OF PURIFYING CYTIDINE DIPHOSPHATE CHOLINE

for which invention we have executed an application for Letters Patent of the United States which was filed on February 8, 2008, under Serial No. 12/063,318; and

WHEREAS,

KYOWA HAKKO KOGYO CO., LTD. of 6-1, Ohtemachi 1-chome, Chiyoda-ku, Tokyo 100-8185 Japan

(full name and address, including postal code, of assignee)

(hereinafter referred to as Assignee) is desirous of acquiring the entire right, title, and interest in and under the invention described in the application for Letters Patent.

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that for good and valuable considerations, the receipt and sufficiency of which are hereby acknowledged, we have assigned and set over, and by this document do assign and set over, to the Assignee and the Assignee's legal representatives, successors and assigns the entire right, title, and interest in and to the invention in the United States the applications for Letters Patent and other such applications (e.g., continuations, continuations-in-part, divisionals and reissues) in the United States, and the Letters Patent, or extensions thereof, that may or shall issue thereon; and we do hereby authorize and request the Commissioner of Patents and Trademarks to issue the Letters Patent to the above-mentioned Assignee agreeably with the terms of this Assignment.

WE HEREBY AUTHORIZE the above-mentioned Assignee to insert in this assignment document the filing date and serial number of the application if the date and number are unknown at the time this assignment is executed.

WE DO HEREBY COVENANT and agree with the Assignee that we will not execute any writing or do any act whatsoever conflicting with the terms of this assignment document set forth herein, and that we will at any time upon request, without further or additional consideration, but at the expense of the Assignee, execute such additional assignments and other writings and do such additional acts as the Assignee may deem necessary or desirable to perfect the Assignee's enjoyment of this grant, and render all necessary assistance in making application for and obtaining original, divisional, continuation, renewal, reissued, or extended Letters Patent of the United States or of any and all foreign countries on the invention, and in enforcing any rights or choses in action accruing as a result of such applications or patents, and by executing preliminary statements and other affidavits, it being understood that the foregoing covenant and agreement shall bind, and inure to the benefit of, the assigns and legal representatives of both parties.

IN WITNESS WHEREOF, we have hereunder set our hands on the dates shown below:

Hideki; Murata
Signature of First Inventor Hideki MURATA

January 11, 2008
Date

Tsuyoshi Mokudai
Signature of Second Inventor Tsuyoshi MOKUDAI

January 12, 2008
Date

Michio Shiomi
Signature of Third Inventor Michio SHIOMI

January 7, 2008
Date

Akihiro Yamao
Witness Date
Akihiro YAMAO January 11, 2008

Kazuo Hibi
Witness Date
Kazuo HIBI January 11, 2008

Shigenori Suga
Witness Date
Shigenori SUGA January 12, 2008

Hiroyuki Jintsu
Witness Date
Hiroyuki JINTSU January 12, 2008

Mitsunori Miyamoto
Witness Date
Mitsunori MIYAMOTO January 7, 2008

Seiji Mikura
Witness Date
Seiji MIKURA January 7, 2008